Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	13098451	(chip die semiconductor device component ic (integrated adj circuit) with (adhesive adhesion))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 20:59
L2	270355	(stuff stuffing stuffed particle) with 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 21:00
L3	4499206	(thickness control height spacing space) same "2"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 20:54
L4	51599	(thickness control height spacing space) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 21:00
L5	22479	(thickness control height spacing space) with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 21:00
L6	216	(thickness) with control with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 20:55
L7	245993	(chip die semiconductor device component ic (integrated adj circuit)) with (adhesive adhesion)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 20:59
L8	7571	(stuff stuffing stuffed particle) with 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 21:13

L9	1136	(thickness control height spacing space) same 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 21:13
L10	627	(thickness control height spacing space) with 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 21:00
L11	12527	(stuff stuffing filler stuffed particle) with 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 21:13
L12	627	(thickness control height spacing space) with 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 21:15
L13	914	(thickness control height spacing space) with 11	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/11 21:15